Specification of Thermoelectric Module

TEHC1-12703

Description

The 127 couples, $40 \text{ mm} \times 40 \text{ mm}$ size single module which is made of our high performance ingot to achieve superior cooling performance and $74 \text{ }^{\circ}\text{C}$ or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

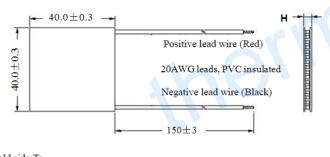
- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

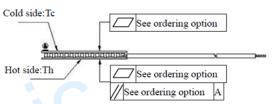
Performance Specification Sheet

Th (C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module
			when cooling capacity is zero at cold side
U_{max} (Voltage)	16.8	18.08	Voltage applied to the module at DT _{max}
I _{max} (Amps)	4.2	4.2	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	44.6	49.0	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	3.03	3.26	The module resistance is tested under AC
Tolerance (%)	±10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters

Manufacturing Options





- A. Solder:
- 1. T100: BiSn (Melting Point=138 °C)
- 2. T200: CuSn (Melting Point= 227 °C)
- **B. Sealant:**
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

- C. Ceramics:
- 1. Alumina (Al₂O₃, white 96%)(AlO)
- 2. Aluminum Nitride (AlN)
- **D. Ceramics Surface Options:**
- 1. Blank ceramics (not metalized)
- 2. Metalized (Copper-Nickel plating)

Ordering Option

Naming for the Module

Suffix	Thickness	Flatness/	Lead wire length (mm)		
	H / (mm)	Parallelism (mm)	Standard/Optional length		
TF	0:4.2±0.1	0:0.05/0.05	150±3/Specify		
TF	1:4.2±0.05	1:0.025/0.025	150±3/Specify		
TF	2:4.2±0.025	2:0.015/0.015	150±3/Specify		
For TF01: Thickness 4.2+0.1(mm) and Flatness 0.025/0.025(mm)					

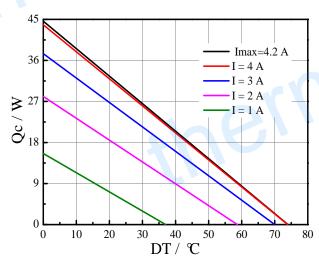
TEHC1-12703- X-X-X-X				
	Ceramics Flatness/ Parallelism			
	Sealant Sealant			
	Solder			
TEHC1-12703-T100-NS -TF01 -AIO				
T100: BiSn (Tmelt=138°C)				
NS: No sealing	AlO: Alumina (Al2O3, white 96%)			
TF01: Thickness $\pm0.1 (mm)$ and Flatness/Parallelism $0.025/0.025 (mm)$				

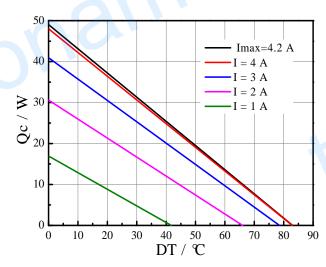
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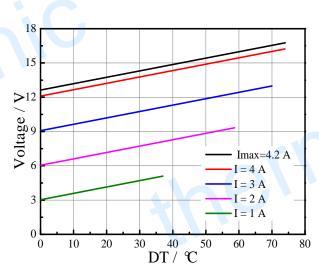
Performance Curves at Th=27 ℃

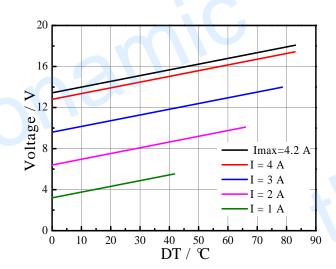
© Performance Curves at Th=50 ℃



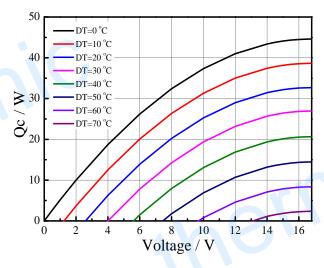


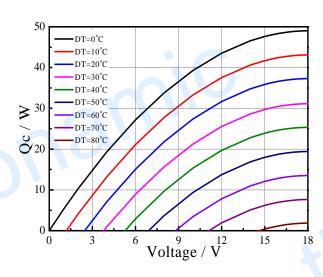
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V = f(DT)





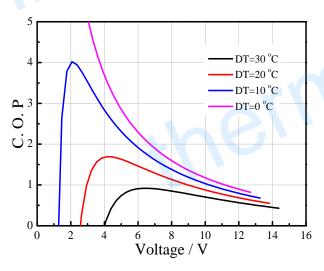
Standard Performance Graph Qc = f(V)

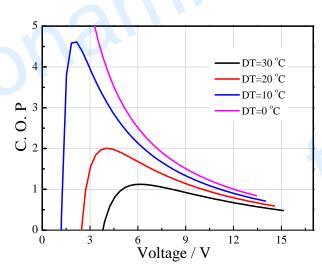
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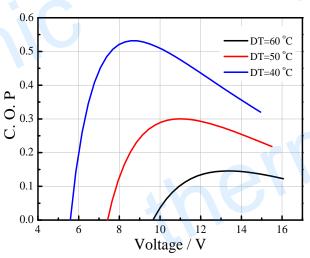
Performance Curves at Th=27 ℃

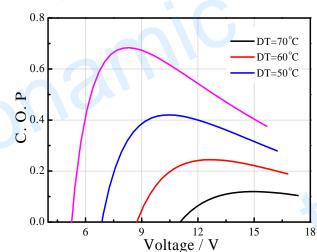
Performance Curves at Th=50 ℃





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC